

Title (en)  
THICKNESS MEASUREMENT WITH INDUCTIVE AND OPTICAL DISPLACEMENT SENSORS

Title (de)  
DICKENMESSUNG MIT INDUKTIVEN UND OPTISCHEN VERDRÄNGUNGSSENSOREN

Title (fr)  
MESURE D'ÉPAISSEUR AVEC CAPTEURS DE DÉPLACEMENT INDUCTIF ET OPTIQUE

Publication  
**EP 3857163 A1 20210804 (EN)**

Application  
**EP 19867836 A 20190924**

Priority  
• US 201862735583 P 20180924  
• US 201916569214 A 20190912  
• US 2019052541 W 20190924

Abstract (en)  
[origin: US2020096308A1] A sensor system includes an eddy current sensor including at least one coil with excitation electronics coupled across the coil. An optical displacement sensor is secured to the eddy current sensor so that a vertical distance between the sensors is fixed. The optical displacement sensor is located on top of and concentric with the coil so that a measurement axis of the optical displacement sensor is collinear with an axis of symmetry of the coil. A computing device including a processor and memory is coupled to receive sensor data from the eddy current sensor and the optical displacement sensor that is adapted for analyzing the sensor data obtained from measuring a coated substrate including a coating layer on at least one side of a metal substrate to determine at least a thickness of the coating layer.

IPC 8 full level  
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CPC (source: EP KR US)  
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